

	Type	L #	Hits	Search T xt	DBs	Time Stamp
1	BRS	L1	733	"solder ball" with (bond\$3 near2 pad\$3)	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2003/07/14 08:47
2	BRS	L154	14	1 and customiz\$8	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2003/07/14 08:48
3	BRS	L155	3860	(screen near2 print\$4) near8 (epoxy or solder)	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2003/07/14 08:53
4	BRS	L156	39	155 and customiz\$4	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2003/07/14 08:50
5	BRS	L157	2778	(screen near2 print\$4) near4 (epoxy or solder)	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2003/07/14 08:54

	Typ	L #	Hits	Search Text	DBs	Time Stamp
6	BRS	L158	127	157 same (electrical\$4 near2 connect\$4)	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2003/07/14 08:55

	Type	L #	Hits	Search Text	DBs
1	IS&R	L160	833	(438/612).CCLS.	USPAT; US-PGP UB
2	IS&R	L162	795	(438/613).CCLS.	USPAT; US-PGP UB
3	IS&R	L163	230	(438/617).CCLS.	USPAT; US-PGP UB
4	IS&R	L164	312	(438/128).CCLS.	USPAT; US-PGP UB
5	IS&R	L165	207	(438/129).CCLS.	USPAT; US-PGP UB
6	IS&R	L166	114	(438/130).CCLS.	USPAT; US-PGP UB
7	IS&R	L167	154	(438/131).CCLS.	USPAT; US-PGP UB
8	IS&R	L168	220	(438/132).CCLS.	USPAT; US-PGP UB
9	IS&R	L169	217	(438/598).CCLS.	USPAT; US-PGP UB
10	IS&R	L170	145	(438/599).CCLS.	USPAT; US-PGP UB
11	IS&R	L171	209	(438/600).CCLS.	USPAT; US-PGP UB
12	IS&R	L172	216	(438/601).CCLS.	USPAT; US-PGP UB

	Type	L #	Hits	Search T xt	DBs	Time Stamp
1	IS&R	L1	257	(438/119).CCLS.	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2003/07/14 17:33
2	IS&R	L8	1626	(438/128).CCLS.	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2003/07/14 18:02

	Type	L #	Hits	Search Text	DBs
4	BRS	L4	6	1 near8 (connect\$4 ) near8 solder\$4	USPAT; US-PG PUB; EPO; JPO; DERWE NT; IBM_TD B
5	BRS	L5	0	1 near8 (interconnect\$4 ) near8 solder\$4	USPAT; US-PG PUB; EPO; JPO; DERWE NT; IBM_TD B
6	BRS	L6	460	pad near2 adjacent\$4 near4 solder\$4	USPAT; US-PG PUB; EPO; JPO; DERWE NT; IBM_TD B

	Typ	L #	Hits	Search Text	DBs
7	BRS	L7	292	pad near2 adjacent\$4 near2 solder\$4	USPAT; US-PG PUB; EPO; JPO; DERWE NT; IBM_TD B
8	BRS	L8	59	pad near adjacent\$4 near solder\$4	USPAT; US-PG PUB; EPO; JPO; DERWE NT; IBM_TD B
9	BRS	L9	2	1 near4 bridg\$4	USPAT; US-PG PUB; EPO; JPO; DERWE NT; IBM_TD B

	Type	L #	Hits	Search Text	DBs
1	BRS	L1	411	(first near2 second! near2 third) near2 pad	USPAT; US-PG PUB; EPO; JPO; DERWE NT; IBM_TD B
2	BRS	L2	7	1 near4 solder\$4	USPAT; US-PG PUB; EPO; JPO; DERWE NT; IBM_TD B
3	BRS	L3	1	1 near8 (between or among) near8 solder\$4	USPAT; US-PG PUB; EPO; JPO; DERWE NT; IBM_TD B

	Typ	L #	Hits	Search T xt	DBs
10	BRS	L10	2881	pad near4 bridg\$4	USPAT; US-PG PUB; EPO; JPO; DERWE NT; IBM_TD B
11	BRS	L11	264	pads! near4 bridg\$4 near4 solder\$4	USPAT; US-PG PUB; EPO; JPO; DERWE NT; IBM_TD B
12	BRS	L13	5	pads! near bridg\$4 near solder\$4	USPAT; US-PG PUB; EPO; JPO; DERWE NT; IBM_TD B



	Typ	L #	Hits	Search T xt	DBs
13	BRS	L12	63	pads! near2 bridg\$4 near2 solder\$4	USPAT; US-PG PUB; EPO; JPO; DERWE NT; IBM_TD B
14	BRS	L14	58	12 not 13	USPAT; US-PG PUB; EPO; JPO; DERWE NT; IBM_TD B
15	BRS	L15	0	1 near4 fillet\$4	USPAT; US-PG PUB; EPO; JPO; DERWE NT; IBM_TD B

	Typ	L #	Hits	S arch T xt	DBs
16	BRS	L16	2	1 near4 short\$4	USPAT; US-PG PUB; EPO; JPO; DERWE NT; IBM_TD B
17	BRS	L17	34	pads! near2 short\$4 near2 solder\$4	USPAT; US-PG PUB; EPO; JPO; DERWE NT; IBM_TD B
18	BRS	L18	8	pads! near short\$4 near solder\$4	USPAT; US-PG PUB; EPO; JPO; DERWE NT; IBM_TD B

	Typ	L #	Hits	S arch T xt	DBs
19	BRS	L19	26	17 not 18	USPAT; US-PG PUB; EPO; JPO; DERWE NT; IBM_TD B
20	BRS	L20	0	1 near8 (fuse or antifuse)	USPAT; US-PG PUB; EPO; JPO; DERWE NT; IBM_TD B
21	BRS	L21	2	1 same (fuse or antifuse)	USPAT; US-PG PUB; EPO; JPO; DERWE NT; IBM_TD B

	Typ	L #	Hits	S arch Text	DBs
22	BRS	L22	791	pads! near8 (fuse or antifuse)	USPAT; US-PG PUB; EPO; JPO; DERWE NT; IBM_TD B
23	BRS	L23	135	pads! near (fuse or antifuse)	USPAT; US-PG PUB; EPO; JPO; DERWE NT; IBM_TD B